



- ☛ Super Low Gate Charge
- ☛ Green Device Available
- ☛ Excellent CdV/dt effect decline
- ☛ Advanced high cell density Trench technology

CST2305 Product Summary

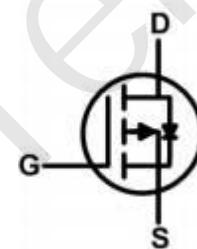


BVDSS	RDS(on)	ID
-20V	45mΩ	-3.5A

CST2305 Description

The CST2305 is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications. The CST2305 meet the RoHS and Green Product requirement with full function reliability approved.

CST2305 SOT 23 Pin Configurations



CST2305 Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.5	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.0	A
I _{DM}	Pulsed Drain Current ²	-10	A
P _D @T _A =25°C	Total Power Dissipation ³	0.90	W
P _D @T _A =70°C	Total Power Dissipation ³	0.54	W
T _{STG}	Storage Temperature Range	-55 to 150	C
T _J	Operating Junction Temperature Range	-55 to 150	C

CST2305 Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	120	C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	95	C/W



CST2305 P-Ch 20V Fast Switching MOSFETs

CST2305 Electrical Characteristics ($T_J=25\text{ C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25C , $I_{\text{D}}=-1\text{mA}$	---	-0.014	---	V/ C
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4.9\text{A}$	---	45	62	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_{\text{D}}=-3.4\text{A}$	---	65	85	
		$V_{\text{GS}}=-1.8\text{V}$, $I_{\text{D}}=-2\text{A}$	---	---	---	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-0.4	---	-1.0	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	3.95	---	mV/ C
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25\text{C}$	---	---	-1	uA
		$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}= \pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	12.8	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	9.2	14.3	nC
Q_{gs}	Gate-Source Charge		---	1.89	2.6	
Q_{gd}	Gate-Drain Charge		---	3.1	4.3	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_{\text{G}}=3.3\Omega$, $I_{\text{D}}=-3\text{A}$	---	5.6	11.2	ns
T_r	Rise Time		---	40.8	73	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	33.6	67	
T_f	Fall Time		---	18	36	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	757	1200	pF
C_{oss}	Output Capacitance		---	104	160	
C_{rss}	Reverse Transfer Capacitance		---	98	151	

CST2305 Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0\text{V}$, Force Current	---	---	-3.5	A
I_{SM}	Pulsed Source Current ^{2,4}		---	---	-10	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25\text{C}$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$I_F=-3\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$,	---	21.8	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25\text{C}$	---	6.9	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150C junction temperature
- 4.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



CST2305 P-Ch 20V Fast Switching MOSFETs

CST2305 Typical Characteristics

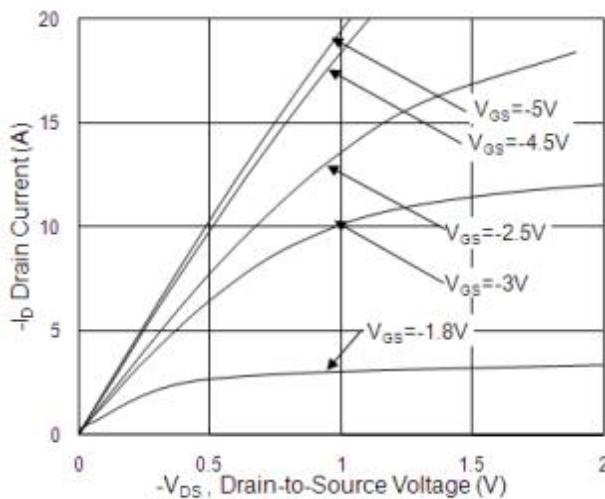


Fig. 1 Typical Output Characteristics

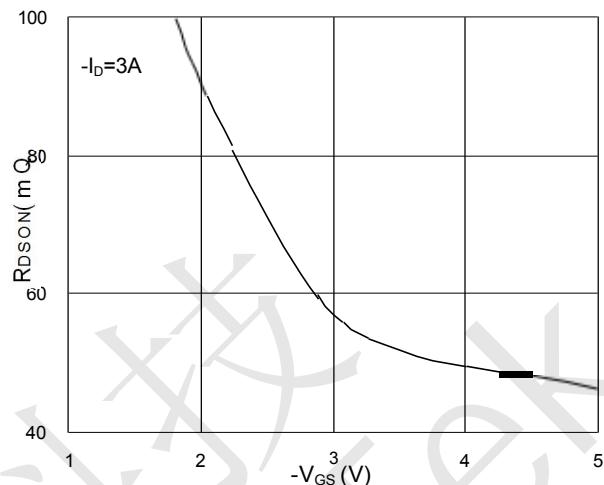


Fig. 2 On-Resistance vs. G-S Voltage

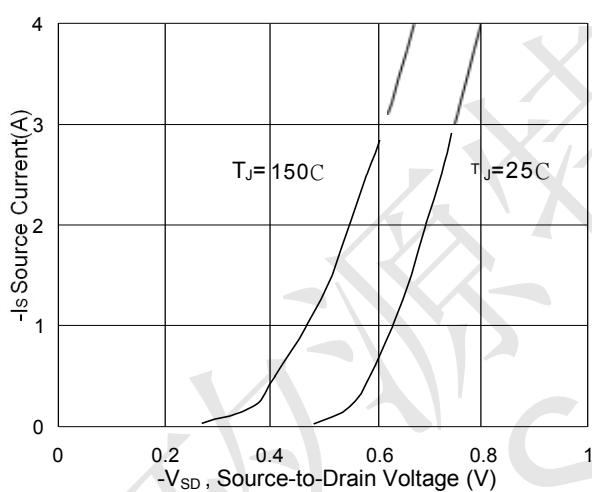


Fig. 3 Forward Characteristics of Reverse

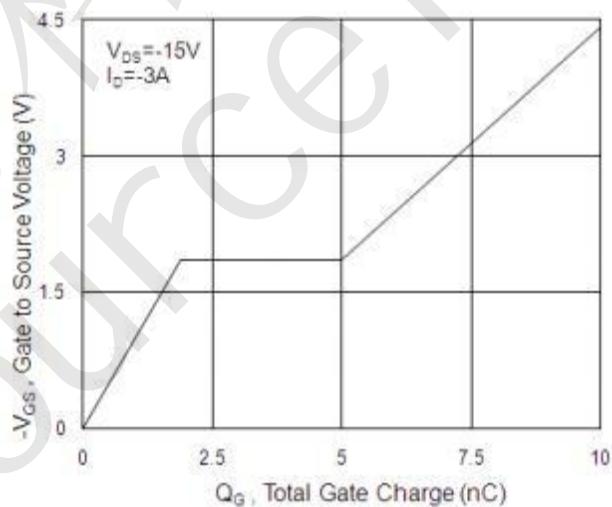


Fig. 4 Gate-charge Characteristics

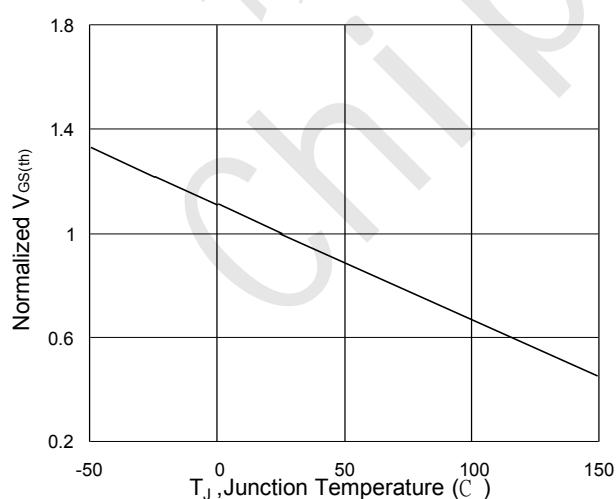


Fig. 5 Normalized $V_{GS(th)}$ vs. T_J

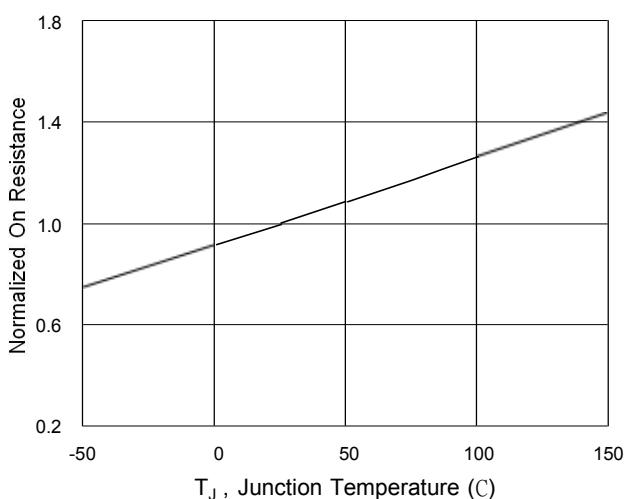


Fig. 6 Normalized $R_{DS(on)}$ vs. T_J



CST2305 P-Ch 20V Fast Switching MOSFETs

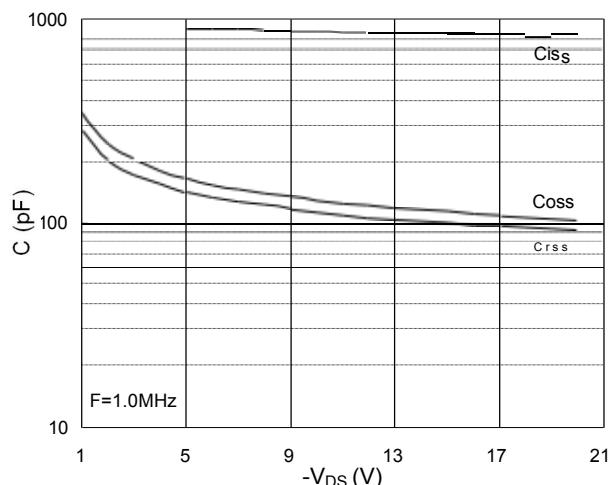


Fig.7 Capacitance

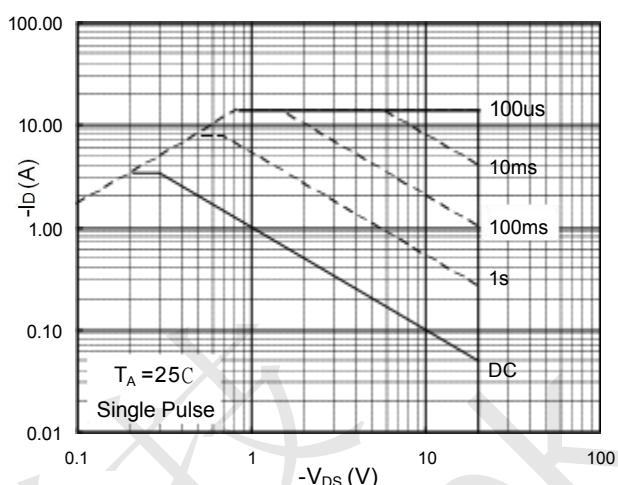


Fig.8 Safe Operating Area

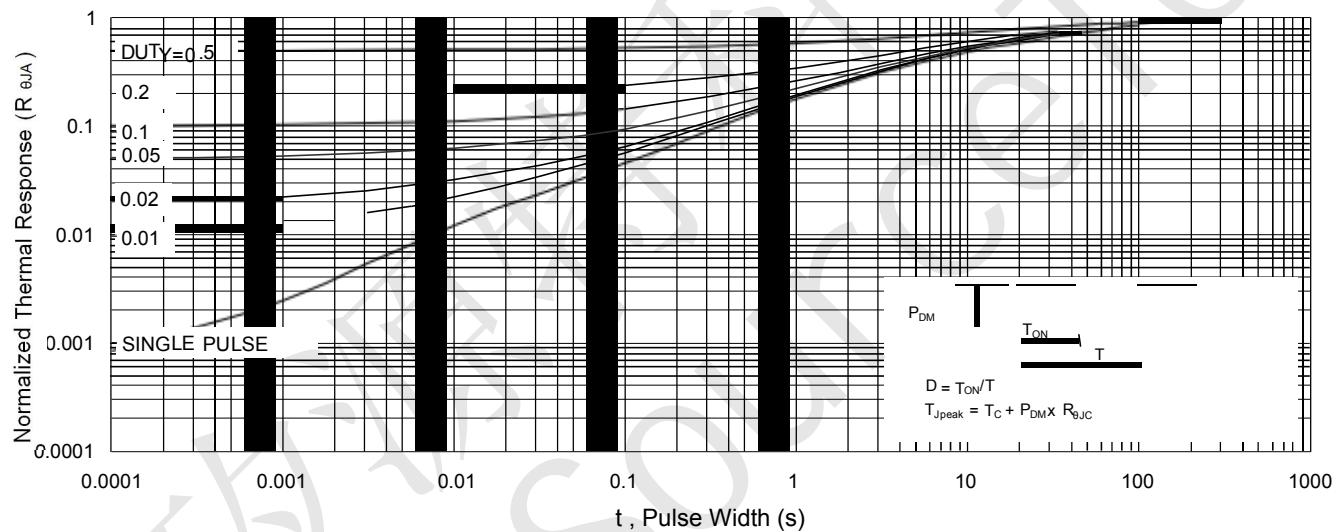


Fig.9 Normalized Maximum Transient Thermal Impedance

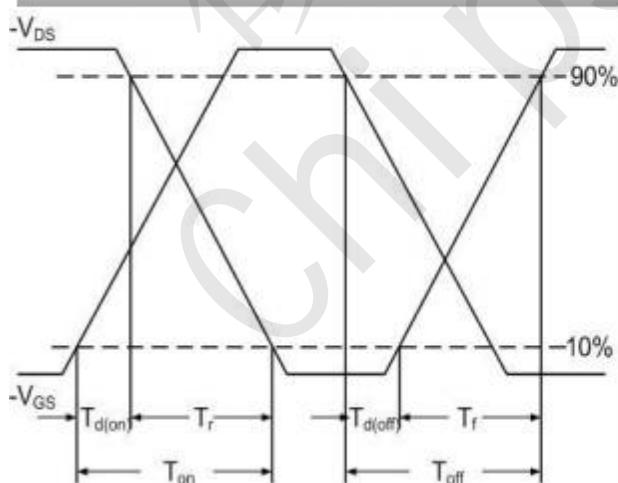


Fig.10 Switching Time Waveform

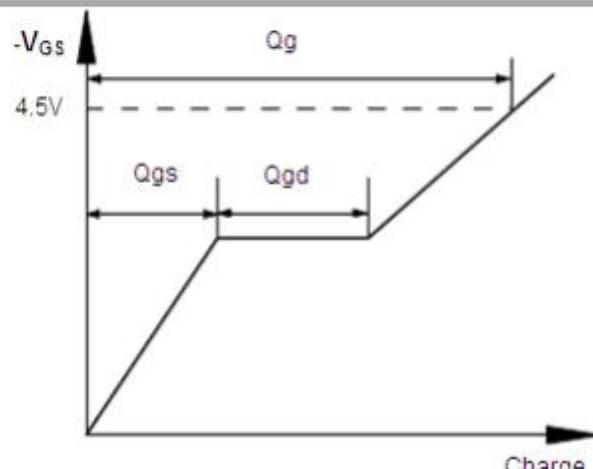
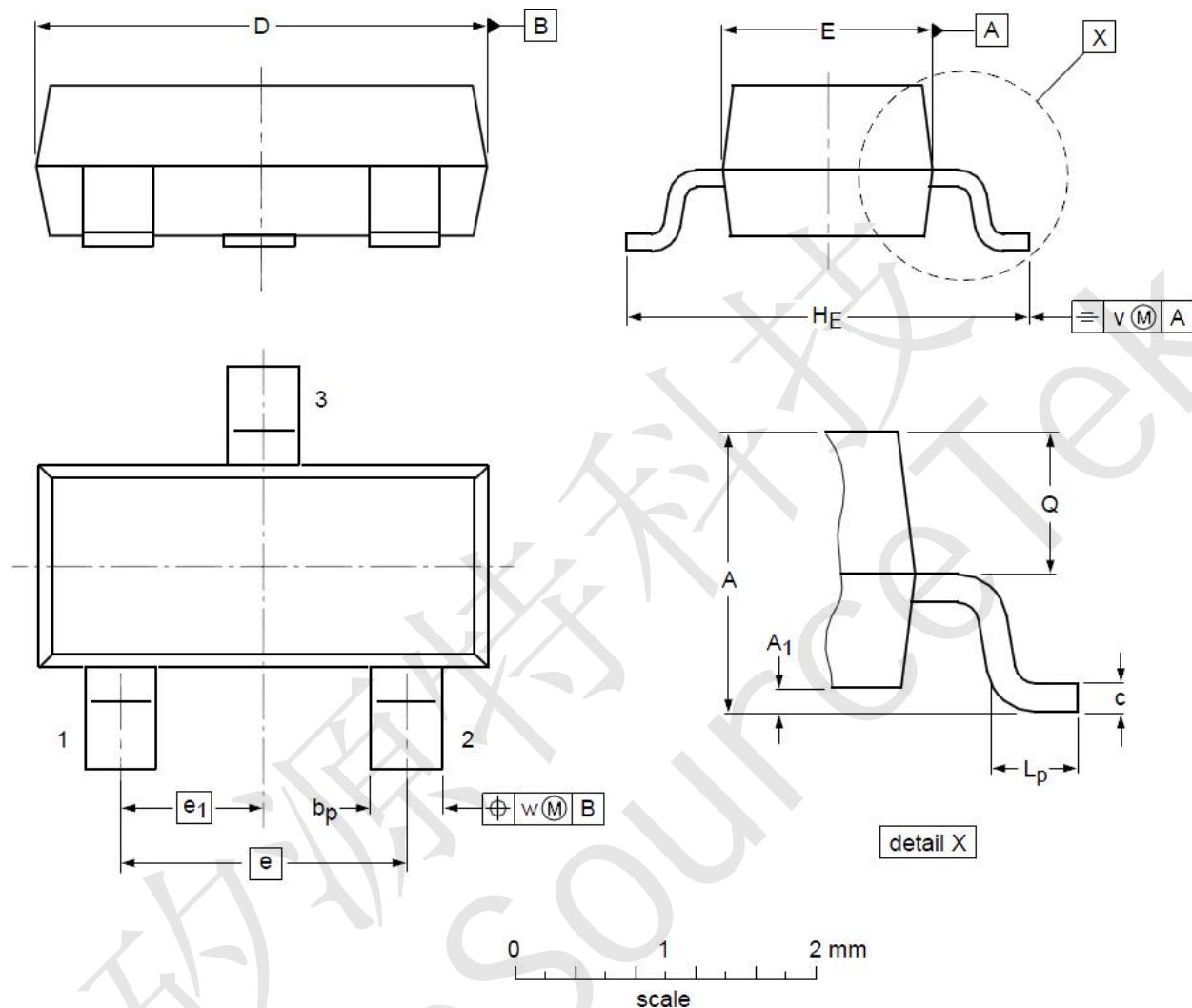


Fig.11 Gate Charge Waveform



CST2305 P-Ch 20V Fast Switching MOSFETs

CST2305 SOT23 Mechanical Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A ₁	0.01	0.05	0.10
b _p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e ₁	--	0.95	--
H _E	2.25	2.40	2.55	L _p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				